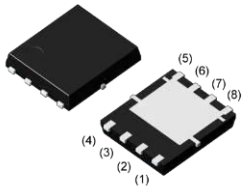
AD40N50D3

40V N-Channel MOSFETs **datasheet**

V_{DSS}	40V
$R_{DS(on)}$(typ.)	4.5mΩ
I_D	50A
P_D	40W

Outline

P PAK 3X3

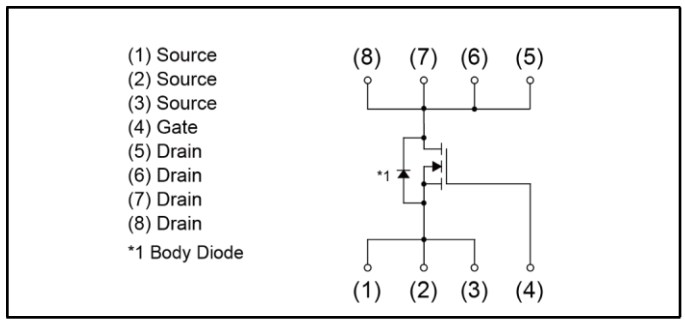


Features

- *40V, 50A, RDS(ON) =4.5mΩ@VGS = 10V*
- *Improved dv/dt capability*
- *Fast switching*
- *Green Device Available*

Applications

- *MB / VGA / Vcore*
- *POL Applications*
- *SMPS 2nd SR*



Type		
	Reel size (mm)	330
	Tape width (mm)	12
	Basic ordering unit (pcs)	5000
	Taping code	D3
	Marking	AD40N50D3

Absolute Maximum Ratings Tc=25℃ unless otherwise noted

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	40	V
V_{GS}	Gate-Source Voltage	+20/-12	V
I_D	Drain Current – Continuous (T_C=25℃)	50	A
	Drain Current – Continuous (T_C=100℃)	32	A
I_{DM}	Drain Current – Pulsed[1]	200	A
EAS	Single Pulse Avalanche Energy[2]	---	mJ
IAS	Single Pulse Avalanched Current[2]	---	A
P_D	Power Dissipation (T_C=25℃)	40	W
	Power Dissipation – Derate above 25℃	0.32	W/℃
T_{STG}	Storage Temperature Range	-55 to 150	℃
T_J	Operating Junction Temperature Range	-55 to 150	℃

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	62	℃/W
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	2.95	℃/W

Electrical Characteristics (T_J=25 ℃, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V , I_D=250uA	40	---	---	V
I_{DSS}	Drain-Source Leakage Current	V_{DS}=40V , V_{GS}=0V , T_J=25℃	---	---	1	uA
		V_{DS}=32V , V_{GS}=0V , T_J=100℃	---	---	10	uA
I_{GSS}	Gate-Source Leakage Current	V_{GS}=20V , V_{DS}=0V	---	---	100	nA

On Characteristics

$R_{DS(ON)}$	Static Drain-Source On-Resistance	V_{GS}=10V , I_D=4A	---	4.5	5.6	mΩ
		V_{GS}=4.5V , I_D=3A	---	7.1	8.8	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	V_{GS}=V_{DS} , I_D =250uA	1.2	1.6	2.5	V
gfs	Forward Transconductance	V_{DS}=10V , I_S=1A	---	4	---	S

Dynamic and switching Characteristics

Q_g	Total Gate Charge[3,4]	V_{DS}=20V , V_{GS}=10V , I_D=20A	---	14	---	nC
Q_{gs}	Gate-Source Charge[3,4]		---	3	---	
Q_{gd}	Gate-Drain Charge[3,4]		---	6	---	
$T_{d(on)}$	Turn-On DelayTime[3,4]	V_{DD}=20V , V_{GS}=10V , R_G=6Ω	---	10	---	ns
T_r	Rise Time[3,4]	I_D=20A	---	14	---	
$T_{d(off)}$	Turn-Off DelayTime[3,4]		---	28	---	
T_f	Fall Time[3,4]		---	20	---	
C_{iss}	Input Capacitance	V_{DS}=20V , V_{GS}=0V , F=1MHz	---	790	---	pF
C_{oss}	Output Capacitance		---	350	---	
C_{rss}	Reverse Transfer Capacitance		---	20	---	
R_g	Gate resistance	V_{GS}=0V, V_{DS}=0V, F=1MHz	---	1.5	---	Ω

Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current	V_G=V_D=0V , Force Current	---	---	50	A
I_{SM}	Pulsed Source Current		---	---	100	A
V_{SD}	Diode Forward Voltage	V_{GS}=0V , I_S=1A , T_J=25℃	---	---	1	V
T_{rr}	Reverse Recovery Time	V_R=30V, I_S=10A	---	---	---	ns
Q_{rr}	Reverse Recovery Charge	di/dt=100A/μs T_J=25℃	---	---	---	nC

Note :
1.Repetitive Rating : Pulsed width limited by maximum junction temperature.
2.V_{DD}=25V,V_{GS}=10V,L=0.1mH,I_{AS}=---A.,R_G=25Ω,Starting T_J=25℃.
3.The data tested by pulsed , pulse width ≦ 300us , duty cycle ≦ 2%.
4.Essentially independent of operating temperature.

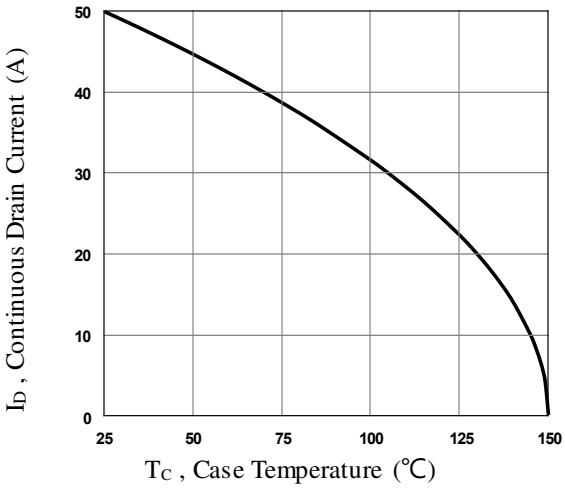


Fig.1 Continuous Drain Current vs. T_C

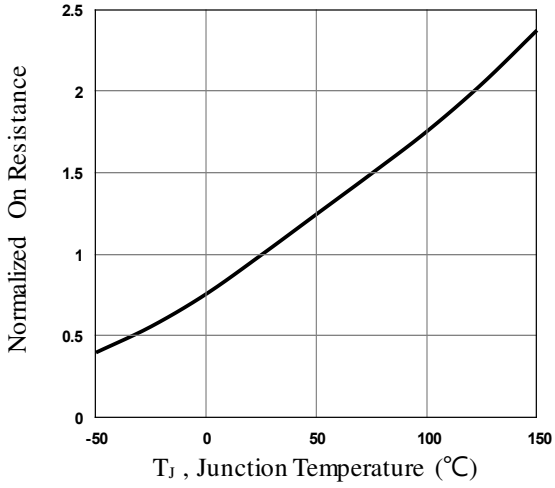


Fig.2 Normalized RDSON vs. T_J

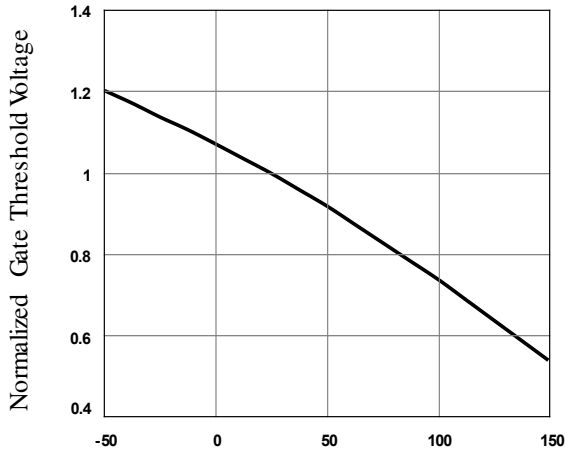


Fig.3 Normalized V_{th} vs. T_J

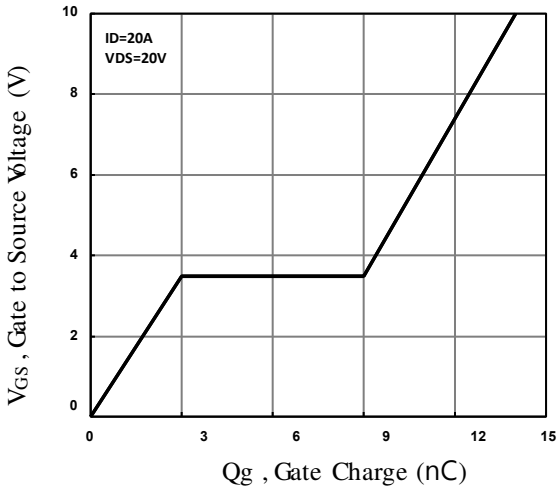


Fig.4 Gate Charge Waveform

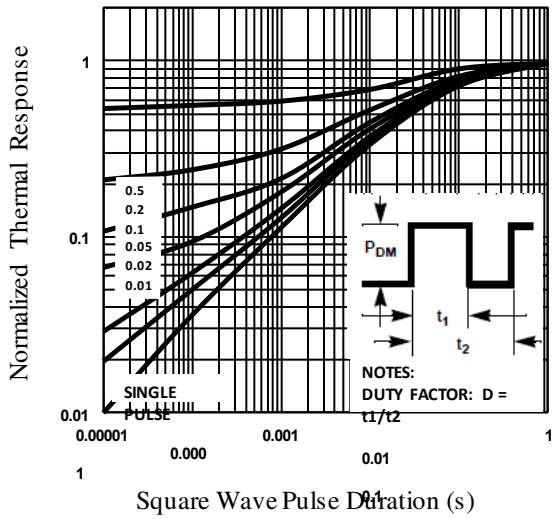


Fig.5 Normalized Transient Impedance

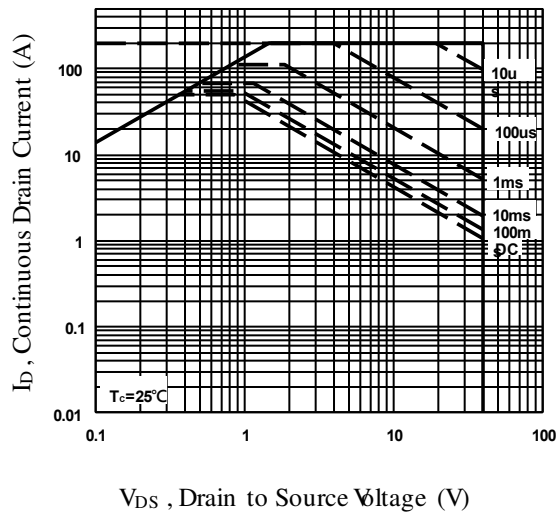


Fig.6 Maximum Safe Operation Area

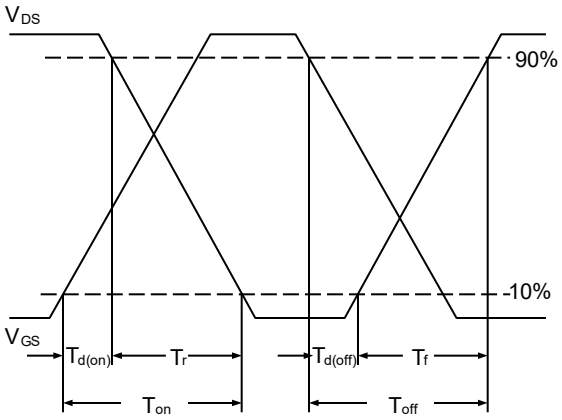


Fig.7 Switching Time Waveform

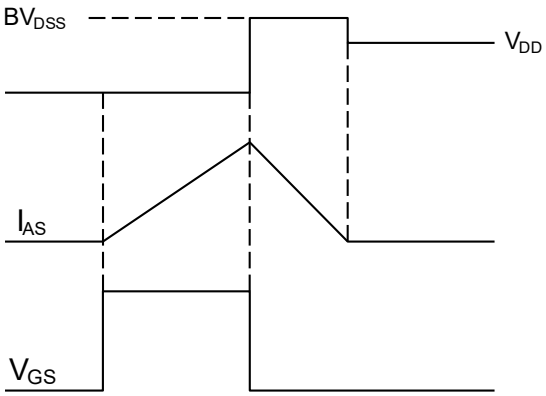
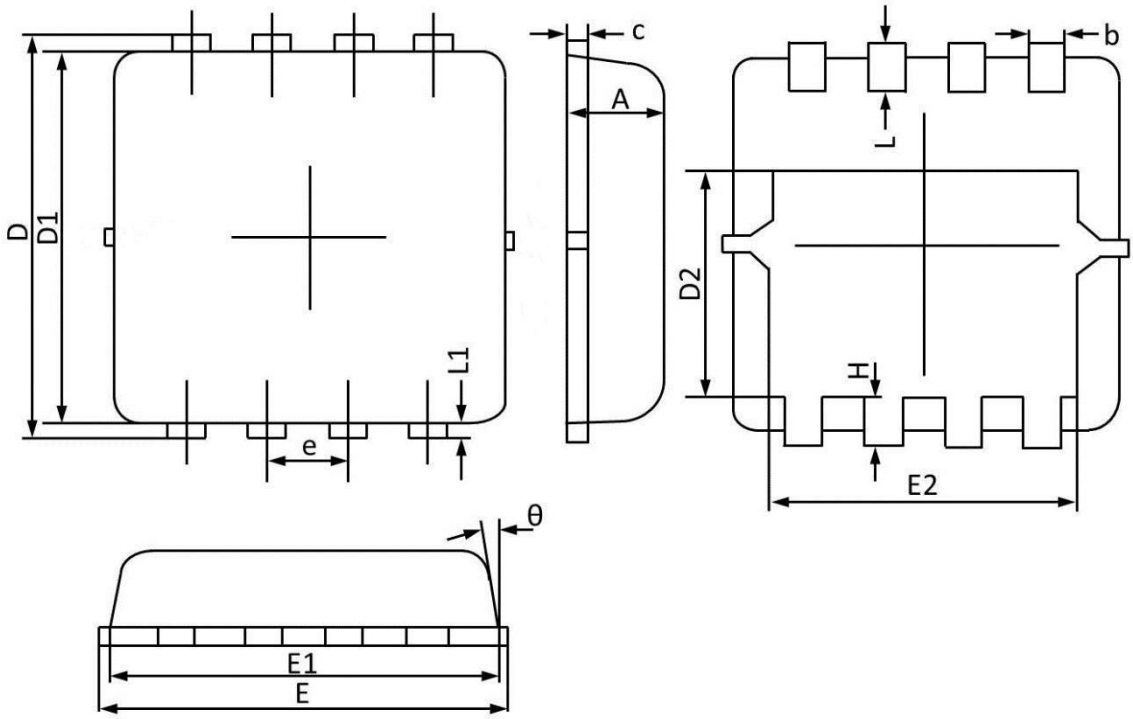


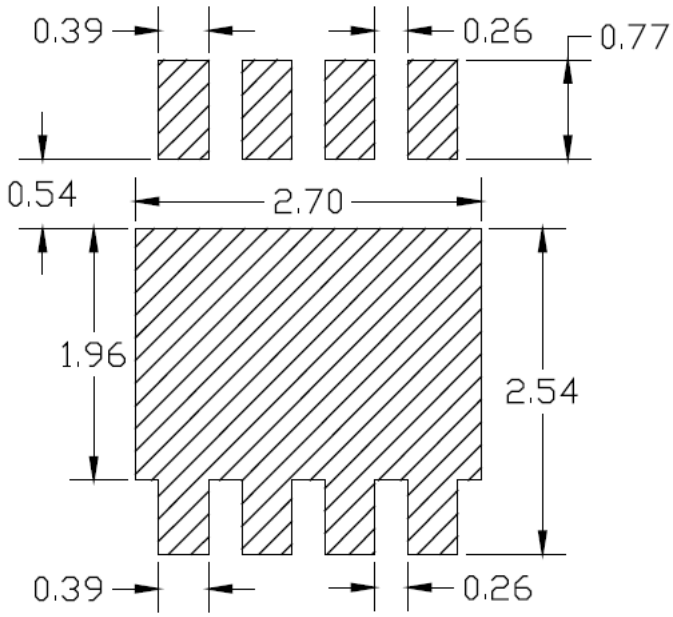
Fig.8 EAS Waveform

PPAK3x3 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	0.900	0.700	0.035	0.028
b	0.350	0.250	0.014	0.010
c	0.250	0.100	0.010	0.004
D	3.500	3.050	0.138	0.120
D1	3.200	2.900	0.126	0.114
D2	1.950	1.350	0.077	0.053
E	3.400	3.000	0.134	0.118
E1	3.300	2.900	0.130	0.114
E2	2.600	2.350	0.102	0.093
e	0.65BSC		0.026BSC	
H	0.750	0.300	0.030	0.012
L	0.600	0.300	0.024	0.012
L1	0.200	0.060	0.008	0.002
θ	14°	6°	14°	6°

PPAK3X3 RECOMMENDED LAND PATTERN



unit : mm